

HSU226

Silicon Schottky Barrier Diode for High Speed Switching

REJ03G0017-0100Z

Rev.1.00

Apr.15.2003

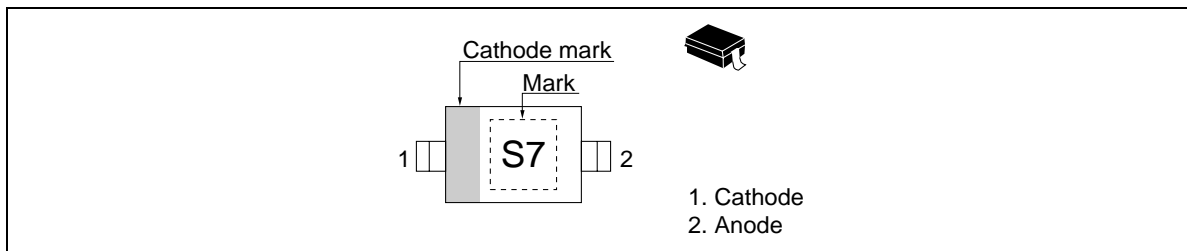
Features

- Low reverse current, Low capacitance.
- Ultra small Resin Package (URP) is suitable for surface mount design.

Ordering Information

Type No.	Laser Mark	Package Code
HSU226	S7	URP

Pin Arrangement



Absolute Maximum Ratings

(Ta = 25°C)

Item	Symbol	Value	Unit
Repetitive peak reverse voltage	V_{RRM}	25	V
Non-Repetitive Peak forward surge current	I_{FSM}^{*1}	200	mA
Forward current	I_F	50	mA
Junction temperature	Tj	125	°C
Storage temperature	Tstg	-55 to +125	°C

Note: 1. 10 ms Sine Wave 1 pulse

Electrical Characteristics

(Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Forward voltage	V_{F1}	—	—	0.33	V	$I_F = 1 \text{ mA}$
	V_{F2}	—	—	0.38	V	$I_F = 5 \text{ mA}$
Reverse current	I_R	—	—	0.45	μA	$V_R = 20 \text{ V}$
Capacitance	C	—	—	2.80	pF	$V_R = 1 \text{ V}, f = 1 \text{ MHz}$

Main Characteristic

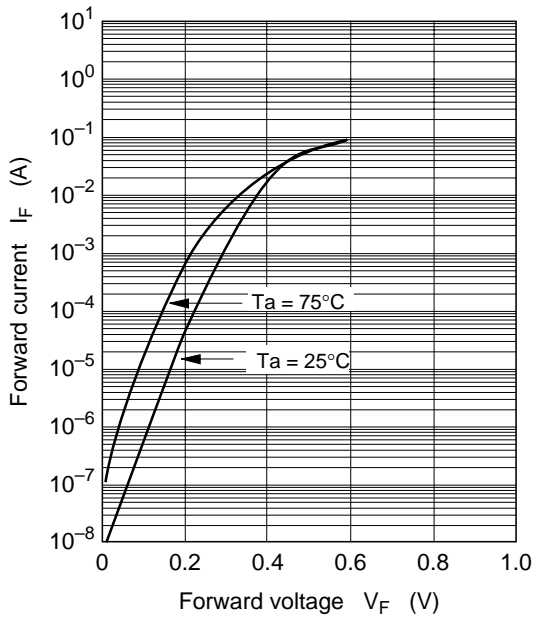


Fig.1 Forward current vs. Forward voltage

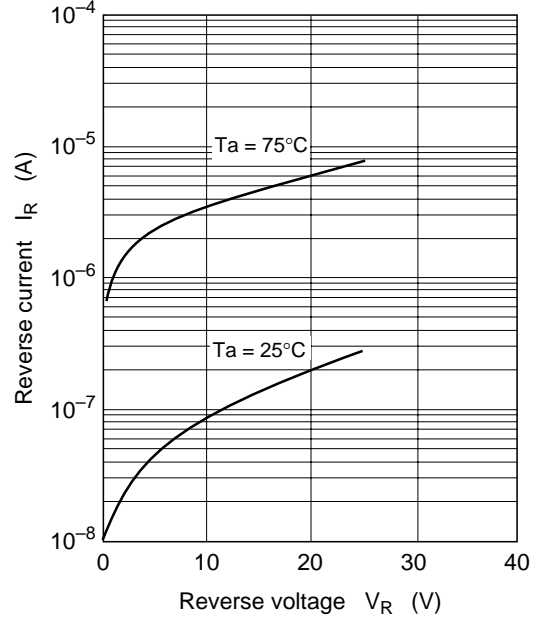


Fig.2 Reverse current vs. Reverse voltage

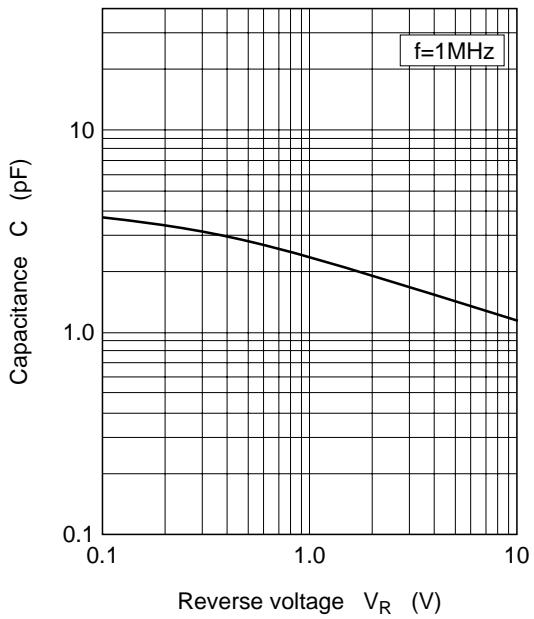
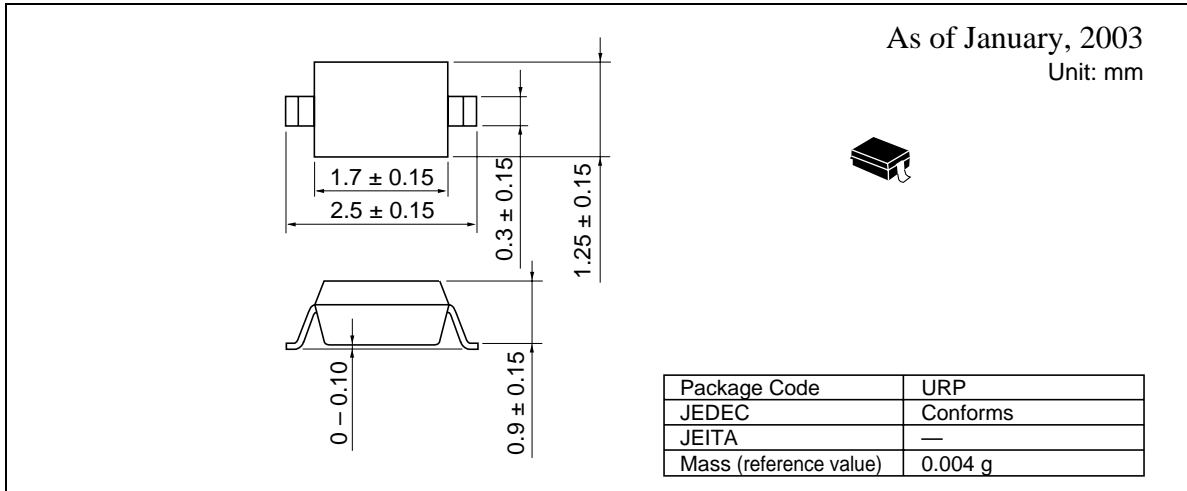


Fig.3 Capacitance vs. Reverse voltage

Package Dimensions



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